



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



preliminary

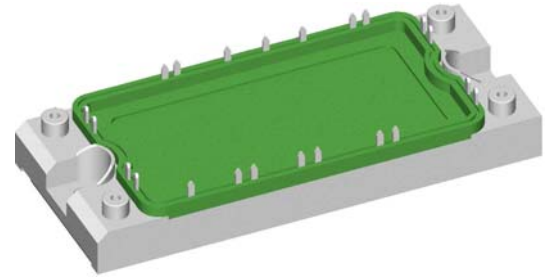
High Voltage Thyristor Module

3~ Rectifier	Brake Chopper
$V_{RRM} = 2200 \text{ V}$	$V_{CES} = 1700 \text{ V}$
$I_{DAV} = 117 \text{ A}$	$I_{C25} = 113 \text{ A}$
$I_{FSM} = 500 \text{ A}$	$V_{CE(sat)} = 2.5 \text{ V}$

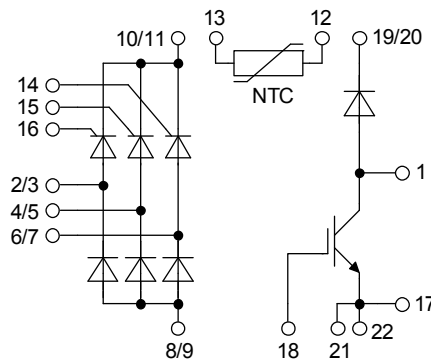
3~ Rectifier Bridge, half-controlled (high-side) + Brake Unit

Part number

MCNA120UI2200TED



Backside: isolated



Features / Advantages:

- Thyristor/Standard Rectifier for line frequency
- Planar passivated chips
- Long-term stability
- Low forward voltage drop
- Leads suitable for PC board soldering
- Copper base plate with Direct Copper Bonded Al₂O₃-ceramic
- Improved temperature and power cycling

Applications:

- Drive Inverters with brake system

Package:

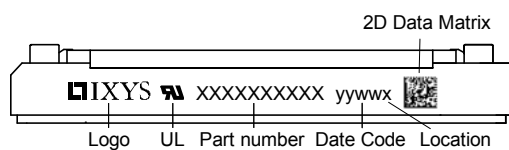
- Housing: E2-Pack
- International standard package
- RoHS compliant
- Isolation voltage: 3600 V~
- Advanced power cycling

Thyristor				Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
$V_{RSM/DSM}$	max. non-repetitive reverse/forward blocking voltage	$T_{VJ} = 25^{\circ}\text{C}$			2300	V	
$V_{RRM/DRM}$	max. repetitive reverse/forward blocking voltage	$T_{VJ} = 25^{\circ}\text{C}$			2200	V	
I_{RD}	reverse current, drain current	$V_{R/D} = 2200\text{ V}$	$T_{VJ} = 25^{\circ}\text{C}$		50	μA	
		$V_{R/D} = 2200\text{ V}$	$T_{VJ} = 125^{\circ}\text{C}$		10	mA	
V_T	forward voltage drop	$I_T = 40\text{ A}$	$T_{VJ} = 25^{\circ}\text{C}$		1.33	V	
		$I_T = 80\text{ A}$			1.70	V	
		$I_T = 40\text{ A}$	$T_{VJ} = 125^{\circ}\text{C}$		1.36	V	
		$I_T = 80\text{ A}$			1.88	V	
I_{DAV}	bridge output current	$T_C = 80^{\circ}\text{C}$ rectangular $d = 1/3$	$T_{VJ} = 150^{\circ}\text{C}$		117	A	
V_{T0}	threshold voltage	} for power loss calculation only	$T_{VJ} = 150^{\circ}\text{C}$		0.83	V	
r_T	slope resistance				13.6	m Ω	
R_{thJC}	thermal resistance junction to case				0.65	K/W	
R_{thCH}	thermal resistance case to heatsink			0.10		K/W	
P_{tot}	total power dissipation		$T_C = 25^{\circ}\text{C}$		190	W	
I_{TSM}	max. forward surge current	$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 45^{\circ}\text{C}$		500	A	
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$		540	A	
		$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 150^{\circ}\text{C}$		425	A	
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$		460	A	
I^2t	value for fusing	$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 45^{\circ}\text{C}$		1.25	kA ² s	
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$		1.22	kA ² s	
		$t = 10\text{ ms}; (50\text{ Hz}), \text{ sine}$	$T_{VJ} = 150^{\circ}\text{C}$		905	A ² s	
		$t = 8,3\text{ ms}; (60\text{ Hz}), \text{ sine}$	$V_R = 0\text{ V}$		880	A ² s	
C_J	junction capacitance	$V_R = 400\text{ V}$ $f = 1\text{ MHz}$	$T_{VJ} = 25^{\circ}\text{C}$		18	pF	
P_{GM}	max. gate power dissipation	$t_p = 30\text{ }\mu\text{s}$	$T_C = 150^{\circ}\text{C}$		10	W	
		$t_p = 300\text{ }\mu\text{s}$			5	W	
P_{GAV}	average gate power dissipation				0.5	W	
$(di/dt)_{cr}$	critical rate of rise of current	$T_{VJ} = 150^{\circ}\text{C}; f = 50\text{ Hz}$ repetitive, $I_T = 120\text{ A}$			150	A/ μs	
		$t_p = 200\text{ }\mu\text{s}; di_G/dt = 0.45\text{ A}/\mu\text{s}$ non-repet., $I_T = 40\text{ A}$			500	A/ μs	
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V_D = 2/3 V_{DRM}$	$T_{VJ} = 150^{\circ}\text{C}$		1000	V/ μs	
		$R_{GK} = \infty$; method 1 (linear voltage rise)					
V_{GT}	gate trigger voltage	$V_D = 6\text{ V}$	$T_{VJ} = 25^{\circ}\text{C}$		1.4	V	
			$T_{VJ} = -40^{\circ}\text{C}$		1.6	V	
I_{GT}	gate trigger current	$V_D = 6\text{ V}$	$T_{VJ} = 25^{\circ}\text{C}$		70	mA	
			$T_{VJ} = -40^{\circ}\text{C}$		150	mA	
V_{GD}	gate non-trigger voltage	$V_D = 2/3 V_{DRM}$	$T_{VJ} = 150^{\circ}\text{C}$		0.2	V	
I_{GD}	gate non-trigger current				5	mA	
I_L	latching current	$t_p = 10\text{ }\mu\text{s}$	$T_{VJ} = 25^{\circ}\text{C}$		150	mA	
		$I_G = 0.45\text{ A}; di_G/dt = 0.45\text{ A}/\mu\text{s}$					
I_H	holding current	$V_D = 6\text{ V}$ $R_{GK} = \infty$	$T_{VJ} = 25^{\circ}\text{C}$		100	mA	
t_{gd}	gate controlled delay time	$V_D = 1/2 V_{DRM}$	$T_{VJ} = 25^{\circ}\text{C}$		2	μs	
		$I_G = 0.45\text{ A}; di_G/dt = 0.45\text{ A}/\mu\text{s}$					
t_q	turn-off time	$V_R = 100\text{ V}; I_T = 40\text{ A}; V_D = 2/3 V_{DRM}$ $di/dt = 10\text{ A}/\mu\text{s}; dv/dt = 20\text{ V}/\mu\text{s}; t_p = 200\text{ }\mu\text{s}$	$T_{VJ} = 150^{\circ}\text{C}$		500	μs	

Brake IGBT				Ratings					
Symbol	Definition	Conditions	min.	typ.	max.	Unit			
V_{CES}	collector emitter voltage	$T_{VJ} = 25^{\circ}\text{C}$			1700	V			
V_{GES}	max. DC gate voltage				± 20	V			
V_{GEM}	max. transient collector gate voltage				± 30	V			
I_{C25}	collector current	$T_C = 25^{\circ}\text{C}$			113	A			
I_{C80}		$T_C = 80^{\circ}\text{C}$			80	A			
P_{tot}	total power dissipation	$T_C = 25^{\circ}\text{C}$			445	W			
$V_{CE(sat)}$	collector emitter saturation voltage	$I_C = 75\text{ A}; V_{GE} = 15\text{ V}$			2.5	V			
					3	V			
$V_{GE(th)}$	gate emitter threshold voltage	$I_C = 3\text{ mA}; V_{GE} = V_{CE}$	5.2	5.8	6.4	V			
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0\text{ V}$			0.6	mA			
					5	mA			
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20\text{ V}$			400	nA			
$Q_{G(on)}$	total gate charge	$V_{CE} = 900\text{ V}; V_{GE} = 15\text{ V}; I_C = 75\text{ A}$		850		nC			
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 900\text{ V}; I_C = 75\text{ A}$ $V_{GE} = \pm 15\text{ V}; R_G = 18\ \Omega$							
t_r	current rise time						$T_{VJ} = 125^{\circ}\text{C}$	220	ns
$t_{d(off)}$	turn-off delay time						100	ns	
t_f	current fall time						880	ns	
E_{on}	turn-on energy per pulse						200	mJ	
E_{off}	turn-off energy per pulse						30	mJ	
			25	mJ					
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15\text{ V}; R_G = 18\ \Omega$							
I_{CM}		$V_{CEK} = 1700\text{ V}$			150	A			
SCSOA	short circuit safe operating area								
t_{SC}	short circuit duration	$V_{CE} = 720\text{ V}; V_{GE} = \pm 15\text{ V}$			10	μs			
I_{SC}	short circuit current	$R_G = 18\ \Omega$; non-repetitive		tbd		A			
R_{thJC}	thermal resistance junction to case				0.28	K/W			
R_{thCH}	thermal resistance case to heatsink				0.10	K/W			
Brake Diode									
V_{RRM}	max. repetitive reverse voltage				1700	V			
I_{F25}	forward current				75	A			
I_{F80}					50	A			
V_F	forward voltage	$I_F = 60\text{ A}$			2.45	V			
					2.60	V			
I_R	reverse current	$V_R = V_{RRM}$			0.1	mA			
					1	mA			
Q_{rr}	reverse recovery charge	$V_R = 900\text{ V}$ $-di_F/dt = 750\text{ A}/\mu\text{s}$ $I_F = 60\text{ A}$							
I_{RM}	max. reverse recovery current						$T_{VJ} = 125^{\circ}\text{C}$	15	μC
t_{rr}	reverse recovery time						60	A	
E_{rec}	reverse recovery energy						550	ns	
R_{thJC}	thermal resistance junction to case				0.65	K/W			
R_{thCH}	thermal resistance case to heatsink				0.10	K/W			

preliminary

Package E2-Pack			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I_{RMS}	RMS current	per terminal			200	A
T_{stg}	storage temperature		-40		125	°C
T_{VJ}	virtual junction temperature		-40		150	°C
Weight				176		g
M_D	mounting torque		3		6	Nm
V_{ISOL}	isolation voltage	t = 1 second	3600			V
		t = 1 minute	3000			V
$d_{Spp/App}$	creepage distance on surface striking distance through air	terminal to terminal	6.0			mm
$d_{Spb/Apb}$		terminal to backside	12.0			mm



Part number

- M = Module
- C = Thyristor (SCR)
- N = High Voltage Thyristor
- A = (≥ 2000 V)
- 120 = Current Rating [A]
- UI = 3~ Rectifier Bridge, half-controlled (high-side) + Brake Unit
- 2200 = Reverse Voltage [V]
- T = Thermistor \ Temperature sensor
- ED = E2-Pack

Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MCNA120UI2200TED	MCNA120UI2200TED	Box	6	510374

Temperature Sensor NTC

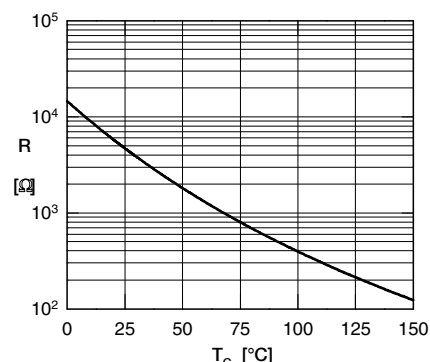
Symbol	Definition	Conditions	min.	typ.	max.	Unit
R_{25}	resistance	$T_{VJ} = 25^\circ$	4.75	5	5.25	k Ω
$B_{25/50}$	temperature coefficient			3375		K

Equivalent Circuits for Simulation

* on die level

$T_{VJ} = 150^\circ\text{C}$

	Thyristor	Brake IGBT	Brake Diode	Unit
V_0	0.83	1.17	1.34	V
R_0	10.5	25	15.2	m Ω



Typ. NTC resistance vs. temperature

Outlines E2-Pack

